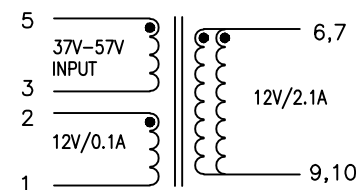


SUGGESTED P.C.B LAYOUT


RECOMMENDED LAND PATTERN

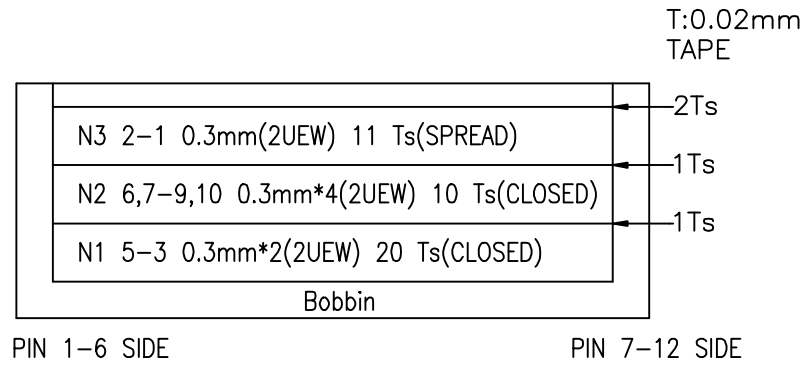
Unit : mm



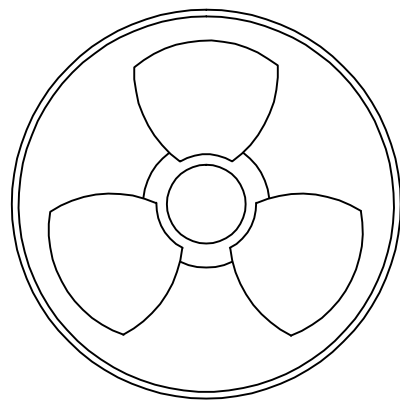
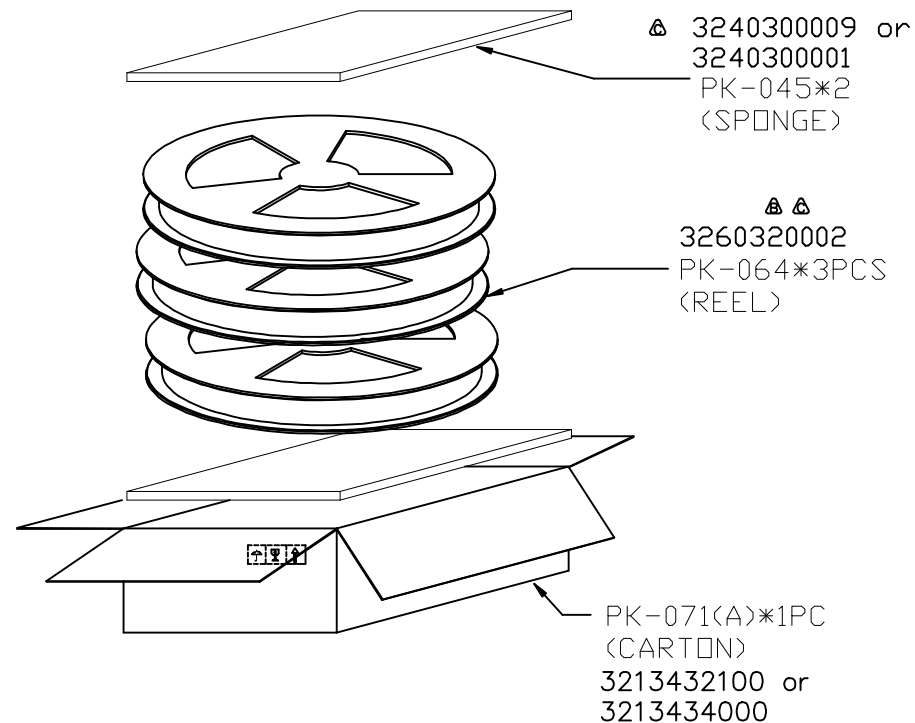
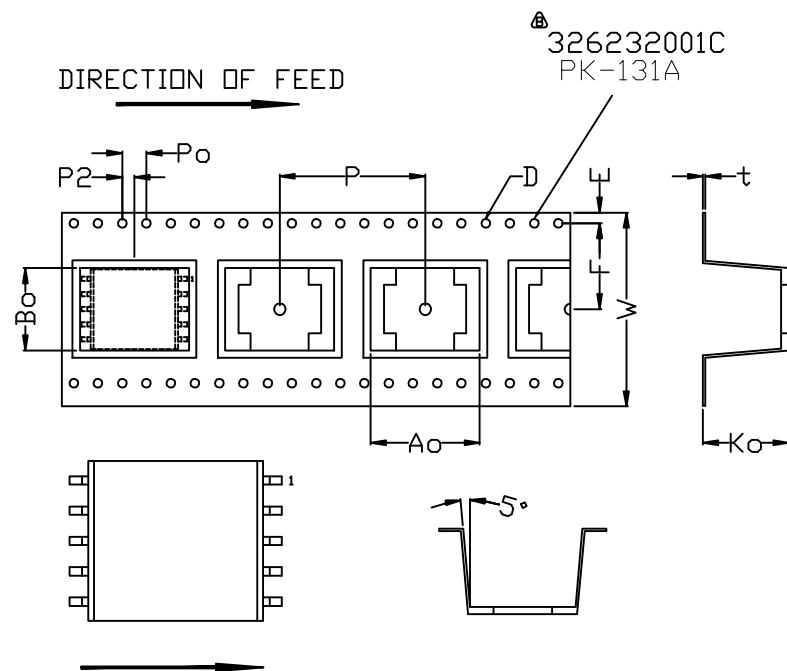
## ELECTRICAL CHARACTERISTICS :

- DCR : PIN 5-3 = 89mΩ MAX.  
PIN 6,7-9,10 = 28mΩ MAX.  
PIN 2-1 = 96mΩ MAX.
- INDUCTANCE : (@100KHz, 0.1Vrms)  
PIN 5-3 = 37uH ±10%
- LEAKAGE INDUCTANCE (@100KHz, 0.1Vrms)  
PIN 5-3 (PIN 1,2,6,7,9,10 SHORT) = 0.85uH MAX.
- TURN RATIO : (@100KHz, 0.1Vrms)  
PIN 5-3 : 6-10 = 2 ±1%  
PIN 5-3 : 2-1 = 1.818 ±1%
- Hi-Pot : (@1000Vac, 10mA, 1Sec) : PIN5+2 TO PIN6+7
- STORAGE TEMPERATURE : -40°C~+85°C  
OPERATING TEMPERATURE : -40°C~+125°C
- RoHS COMPLIANT

								TITLE Flyback Transformer	
								DWG. NO. ATS-1324R	
	RELEASE	01/06/2014	SHIRLEY	DICK	DICK	UNITS: M/M	SAFETY		SHEET 1 of 2
NO:	DESCRIPTION	DATE	BY	CHK	APPD	DATE 01/06/14	P/N:	DRAW SHIRLEY	
REVISIONS									



						<div> <div>AOEM</div> <div> <div></div> <div></div> </div> </div>	TITLE Flyback Transformer	
							DWG. NO. ATS-1324R	
	RELEASE	01/06/2014	SHIRLEY	DICK	DICK	UNITS: M/M	SAFETY	
NO:	DESCRIPTION	DATE	BY	CHK	APPD	DATE 01/06/14	P/N:	SHEET 1 of 2
REVISIONS								DRAW SHIRLEY



REEL

每捲放乾燥包1pcs 用真空袋抽真空封口  
2780000000  $\Delta$  3255048421 or 3255048420

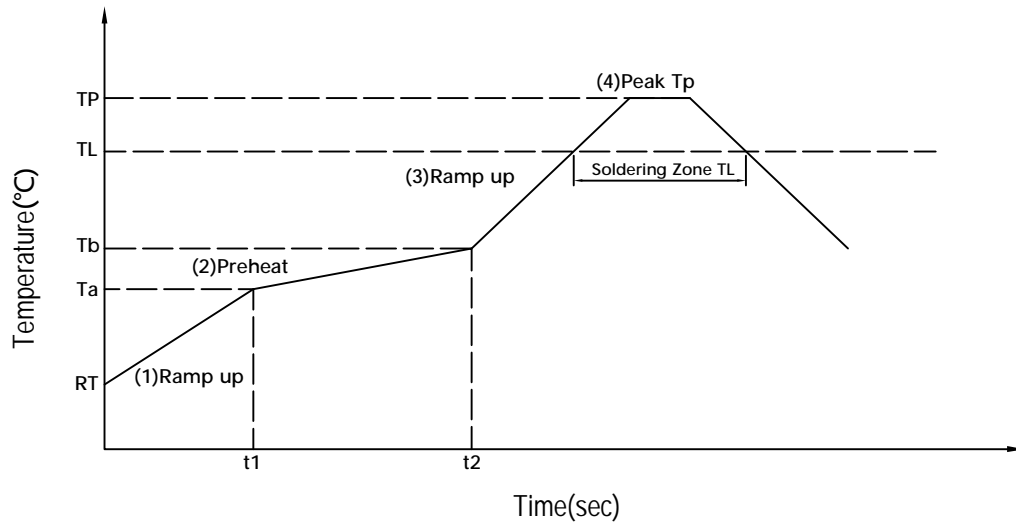
ITEM	W	Ao	Bo	Ko	P	F	E	D	D1	Po	P2	t
DIM	32.00 <sup>+0.30</sup> <sub>-0.30</sub>	18.00 <sup>+0.10</sup> <sub>-0.10</sub>	13.60 <sup>+0.10</sup> <sub>-0.10</sub>	14.10 <sup>+0.10</sup> <sub>-0.10</sub>	24.00 <sup>+0.10</sup> <sub>-0.10</sub>	14.20 <sup>+0.10</sup> <sub>-0.10</sub>	1.75 <sup>+0.10</sup> <sub>-0.10</sub>	1.50 <sup>+0.10</sup> <sub>-0.00</sub>	2.00 <sup>+0.25</sup> <sub>-0.00</sub>	4.00 <sup>+0.10</sup> <sub>-0.10</sub>	2.00 <sup>+0.10</sup> <sub>-0.10</sub>	0.40 <sup>+0.05</sup> <sub>-0.05</sub>

ONE REEL 200 PCS  
ONE CARTON 3 REEL (600 PCS)

C	CHANGE PART NO.	03/06/2012	SHIRLEY	JOAN	JOAN		TITLE		PACKING	
B	CHANGE PART NO.	03/11/2011	SHIRLEY	DICK	DICK		DWG. NO.		968TS71800	
A	ADD SPONG&CARTON	10/04/2005	BART	PAIR	SUEDY		UNITS:		SAFETY	
	RELEASE	04/13/2006	PAIR	AL	EUGENE		M/M			
NO	DESCRIPTION	DATE	BY	CHK	APPD		DATE		SHEET 1 OF 1	
REVISIONS							04/13/06		DRAW	
									Pair	



## Pb-free Soldering IR Reflow(SMD)



- 1,MSL Grade: 1 Level      2,Floor life: 2years      3,Condition:≤30°C RH 85%  
2,Form-1(Reference JEDEC J-STD-020D Table 5-2)

IR reflow profile		Pb-free
step#	Profile Feature	Condition/Duration
step1	Ramp-up rate	3°C/second max
step2	Preheat:150°C-200°C(Ta-Tb)	t1-t2:60-120seconds
step3	Ramp-up rate(TL to Tp)	3°C/second max
	Temperature maintained above 217°C	60-150seconds
step4	Peak temperature(Tp)	260+0/-5°C
	Time within 5°C of actual peak temperature	30seconds max
Ramp-down rate(Tp to TL)		6°C/second max

- 3,Form-2(Reference JEDEC J-STD-020D Table 4-2)

Package Thickness	Volume mm <sup>3</sup> <350	Volume mm <sup>3</sup> 350-2000	Volume mm <sup>3</sup> >2000
<1.6mm	260+0/-5°C	260+0/-5°C	260+0/-5°C
1.6mm-2.5mm	260+0/-5°C	250+0/-5°C	245+0/-5°C
>2.5mm	250+0/-5°C	245+0/-5°C	245+0/-5°C